



## Material Content Data Sheet



<b>Sales Product Name</b>		BAT 15-02LS E6433		<b>Issued</b>		4. July 2019		
<b>MA#</b>		MA005337220						
<b>Package</b>		PG-TSSLP-2-1		<b>Weight*</b>		0.15 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.000	0.23		2306	
	noble metal	gold	7440-57-5	0.001	0.89		8932	
	inorganic material	silicon	7440-21-3	0.017	10.90	12.02	109050	120288
leadframe	non noble metal	nickel	7440-02-0	0.036	24.03	24.03	240265	240265
wire	noble metal	gold	7440-57-5	0.003	1.69	1.69	16913	16913
encapsulation	inorganic material	antimonytrioxide	1309-64-4	0.000	0.03		271	
	organic material	carbon black	1333-86-4	0.001	0.54		5371	
	plastics	epoxy resin	-	0.011	7.25		72475	
	inorganic material	silicondioxide	60676-86-0	0.069	45.87	53.69	458748	536865
leadfinish	noble metal	gold	7440-57-5	0.004	2.72	2.72	27173	27173
plating	noble metal	palladium	7440-05-3	0.001	0.94		9362	
	noble metal	silver	7440-22-4	0.007	4.91	5.85	49134	58496
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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